TF-3050

SERIES 3 LDP10TQ THICK FILM CHIP TRIMMER



The **TF-3050 Series 3 LDP10TQ** provides high accuracy performance to overcome the new challenges of smaller geometries of chip resistor trimming. Proprietary designs achieve the high accuracy mechanical positioning and ultra-stable laser beam control demanded by industry. **TF-3050 S3** utilizes vision registration theta rotation within a Windows XP operating system. These advance features are integrated with established substrate handling and automation systems.

TF-3050 SERIES 3 LDP15TQ THICK FILM CHIP TRIMMER - SPECIFICATIONS

Optical System

Beam Positioned: Precision high-speed galvanometer

Field Size: 12 x 90mm
Resolution: 1.5μm
Repeatability: 2.5 μm

Spot Size: 18 - 40 μm (standard 1064nm)
 Focus Len: 125 mm flat telecentric type

Laser System

• Laser Type: Diode pumped Q-switched

• Output Power: 6W (Q-Switched Avg. Power @ 10 KHz)

Wavelength: Standard 1064nmPulse Width, nominal: 150 nsec

Power Measurement: Thermal pickup

Step & Repeat

■ Type: DC Brushless Linear Motor

Drive Type: Linear Drive

Mechanism per System: Single

Wafer Clamping: Center or Side clamping

■ Travel Speed: 1500 mm/sec

Acceleration: 1.2 GResolution: 1 µm

■ Index Time (1.5mm): 30 msec

Handler

Single stacked elevator: Standard

Drive Type: Stepper Drive
Pick & Place: Stepper Motor
Transfer Cycle: 1~2 sec

• Cartridge Capacity: 360pcs (0402)

■ Elevator: Stepper Motor

Measurement System

■ Dual Mode: Force Current & Force Voltage

Range: 0.1Ω ~ 30 MΩ,
Accuracy: 0.02% Midrange
Repeatability: 0.01% Midrange

Resolution: 0.005%

Measurement Time: 50 μsec

Calibration Standards: 6 pcs 0.01%
Guard Drive Current: 100 mA

■ Guard Offset: 1 mV

Switching Matrix

• Pins per Card: 16

Lines per Pin: 3 (Force, Sense or Guard)
Cards per System (Standard): 6 pcs std, 12 pcs

mavimum

Switch Type: Dry Reed Relay
 Contact Life: 1 Billion Cycles
 Insulation: > 10 GΩ

• Switching Time: 200 µsec

Controller

Intel Core 2 duo processor for main application

Pentium processor for trim engine

Software

WinLts 3 Windows XP Application Software

Special Features

Dimensions: 1310mm x 1028 mm x 1800mm

Weight: 900kg

Utilities Requirements

● Power: 220 V AC, single phase, 10A (50/60Hz)

● Air: 80~100 psi / flow rate 10 cfm

 Vacuum: 100 CFM factory vacuum for debris remove and substrates retention



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